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101648746

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Hidekazu Watanabe

3/08/01

2. Name and address of receiving party(ies):

Sony Corporation

Additional name(s) of conveying party(ies) attached?

☐ No ☐ Yes

Internal Address:

3. Nature of Conveyance:

- ☒ Assignment ☐ Change of Name
☐ Security Agreement
☐ Other
☐ Merger

Street Address: **6-7-35 Katashingawa
Shinagawa-ku**

City: **Tokyo** Country: **Japan** ZIP: **141**

Execution Date: **02/23/01**

Additional name(s) & address(es) attached? ☐ No ☒ Yes

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

02/28/01

A. Patent Application No.(s)

B. Patent No.(s)

09802417

Additional numbers attached?

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Blakely, Sokoloff, Taylor & Zafman LLP**

Internal Address:

Street Address: **12400 Wilshire Boulevard
7th Floor**

City: **Los Angeles** State: **CA** ZIP: **90025**

6. Total number of applications and patents involved:

1

7. Total Fee (37 CFR 3.41).....\$ **40.00**

- ☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit Account Number:

02-2666

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.

Thinh V. Nguyen, Reg. No. 42,034

Name of Person Signing

[Signature]
Signature

March 8, 2001

Date

Total number of pages including cover sheet, attachments, and document: **4**

Mail documents to be recorded with required cover sheet information to:
Assistant Commissioner of Patents, Box Assignments
Washington, D.C. 20231

Attorney Docket No. **80398P348**

PATENT
REEL: 011610 FRAME: 0105

RECORDATION FORM COVER SHEET - PAGE 2

Sony Electronics, Inc.
A Delaware corporation
1 Sony Drive
Park Ridge, New Jersey 07656

Attorney Docket No. 80398P348

PATENT
REEL: 011610 FRAME: 0106

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **EFFECTIVE BUS UTILIZATION USING BUS ARBITER** for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 6-7-35 Kitashingawa, Shinagawa-ku, Tokyo, 141 Japan and Sony Electronics, Inc., a Delaware corporation, with offices at 1 Sony Drive, Park Ridge, New Jersey 07656 (hereinafter referenced as Assignees) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation relate thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: ____, Filing Date: ____.

This assignment executed on the dates indicated below:

Hidekazu Watanabe

Name of First/Joint Inventor

Execution Date of U.S. Patent Application

San Diego, California USA

Residence of First/Joint Inventor



Signature of First/Joint Inventor

2/23/01

Date of This Agreement

Name of Second/Joint Inventor

Execution Date of U.S. Patent Application

Residence of Second/Joint Inventor

Signature of Second/Joint Inventor

Date of This Agreement